

MPCB Capability

Base Material		Aluminum(Larid, Ventec,Yugu Boyu), Iron and Copper isolation base
Max dimension		1200mm* 300mm
Copper foil thickness		0.5-10OZ
Dielectric thickness		0.075-0.15mm
Finish Thickness		0.5-3.2mm (+/-10%)
line width/Gap	1OZ	0.15/0.12MM
	2OZ	0.18/0.15MM
	3OZ	0.25/0.2MM
	4oz	0.3/0.25MM
Soldermask opening		0.05mm
Surface finish		ENIG,OSP,HASL(LF HASL),Immersion Tin,Immersion Silver
Peel strength		$\geq 1.8 \text{ N/mm}$
Surface resistance		$\geq 1*10^5 \text{ M}$
Volume resistivity		$\geq 1*10^6 \text{ M}$
Solder float		260℃,10Min ,No layerig,No sparkling
Permittivity		≤ 4.4
Disspation factor		≤ 0.03
Thermal conductivity		1.0~4.2W/m.k
Hi-pot Withstand		2~6KV
Surface Finish	HASL	SMD 40-2000u", GND 30-800u"
	LF HASL	SMD 40-2000u", GND 30-800u"
	ENIG	Au 1-5u", Ni 80-200u"
	OSP	